



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20260429003.0
Datasheet for INA148, XTR105, XTR11x, and XTR117
Information Only**

Date: April 30, 2026

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20260429003.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
XTR117AIDGKR	
XTR115U/2K5	
XTR116U/2K5	
XTR116UA/2K5	
XTR117AIDGKR	
XTR105UA/2K5	
INA148UA/2K5	
XTR115UA/2K5	
XTR116UA/2K5	
XTR105PA	
XTR116U/2K5	
INA148UA	
INA148UA/2K5	
XTR117AIDRBR	
INA148UA/2K5G4	
XTR105PA	
XTR115UA/2K5	

Technical details of this Product Change follow on the next page(s).

Notification Number:	20260429003.0	Notification Date:	April 30, 2026
Title:	Datasheet for INA148, XTR105, XTR11x, and XTR117		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



INA148

SBOS123A – DECEMBER 1999 – REVISED DECEMBER 2025

Changes from Revision * (October 2000) to Revision A (December 2025)

Page

• Updated <i>Applications</i> links.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Added Pin Configuration and Functions section.....	2
• Added chip site origin (CSO) note to <i>Specification</i> section for clarity.....	3
• Removed separate Electrical Characteristics Table for Single Supply +5V Supply Range. Added relevant single supply parameters to the combined table.....	4
• Added additional test conditions on header and throughout table in <i>Electrical Characteristics</i> and <i>Typical Characteristics</i> for clarity.....	4
• Changed from <i>Offset Voltage vs Power Supply</i> to <i>Power-supply rejection ratio</i> for more clarity.....	4
• Added additional fabrication process specification for Power-Supply Rejection Ratio in <i>Electrical Characteristics</i> table.....	4
• Added test condition "T _A = –40°C to +85°C" for "Gain error vs temperature" in <i>Electrical Characteristics</i> and renamed to "Gain error drift" for clarity.....	4
• Added test condition "Continuous to VS / 2" to short-circuit current specification in <i>Electrical Characteristics</i> for clarity.....	4
• Added additional fabrication process specification for Short Circuit current in <i>Electrical Characteristics</i> table.....	4
• Added additional fabrication process specification for Bandwidth in <i>Electrical Characteristics</i> table.....	4
• Added additional fabrication process specification for 0.1% and 0.01% Settling Time in <i>Electrical Characteristics</i> table.....	4
• Changed overload recovery dual supply CSO:SHE specification from 21μs to 4μs to accurately reflect the specification in the <i>Electrical Characteristics</i> table.....	4
• Added additional fabrication process specification for Overload Recovery in <i>Electrical Characteristics</i> table.....	4
• Changed overload recovery for single supply from 13μs to 3μs to accurately reflect the specification in <i>Electrical Characteristics</i> table.....	4
• Moved power supply, operating and specification temperature range specifications from <i>Electrical Characteristics</i> to <i>Recommended Operating Conditions</i> table.....	4
• Added all chip site origin (CSO) to typical test conditions in <i>Typical Characteristics</i> section	6
• Added chip site origin (CSO) note to Gain vs Frequency, Common-Mode Rejection vs Frequency, Power-Supply Rejection vs Frequency, Short-Circuit Current vs Temperature, Output Voltage Swing vs R _L , Large-Signal Capacitive Load Response, and Overload Recovery Time in <i>Typical Characteristics</i> section	6
• Added additional fabrication process curve for Gain vs Frequency, Common-Mode Rejection vs Frequency, Power-Supply Rejection vs Frequency, Short-Circuit Current vs Temperature, Output Voltage Swing vs R _L , Large-Signal Capacitive Load Response, and Overload Recovery Time in <i>Typical Characteristics</i> section	6
• Updated <i>Application Information</i> verbiage for more clarity.....	12
• Added device nomenclature for chip site origin in <i>Device Support</i>	18

Changes from Revision C (October 2024) to Revision D (December 2025)	Page
• Updated end equipment links in <i>Applications</i>	1
• Added description of device flow information in <i>Specifications</i>	4
• Added all chip site origin (CSO) to typical test conditions in <i>Electrical Characteristics</i>	5
• Added additional fabrication process specification for Input Bias Current and Input Bias Current vs temperature in <i>Electrical Characteristics</i> table.....	5
• Added additional fabrication process specification for Input Offset Current vs temperature in <i>Electrical Characteristics</i> table.....	5
• Added additional fabrication process specification for Offset Voltage and Offset Voltage vs temperature in <i>Electrical Characteristics</i> table.....	5
• Added additional fabrication process specification for Current Source Accuracy vs Power Supply, V+ in <i>Electrical Characteristics</i> table.....	5
• Added all chip site origin (CSO) to typical test conditions in <i>Typical Characteristics</i>	7
• Added additional fabrication process curve for Step Response, Input Bias and Offset Current vs Temperature, and Input Offset Voltage Drift in <i>Typical Characteristics</i>	7
• Updated Overscale Current vs Temperature, Underscale Current vs Temperature, Zero Output Current Error vs Temperature, V _{REG} Output Voltage vs V _{REG} Output Current, and Reference Current Error vs Temperature to align with absolute maximum temperature rating in <i>Typical Characteristics</i>	7
• Added part number fabrication process information table in <i>Device Support</i>	25

Changes from Revision B (March 2022) to Revision C (January 2026)	Page
• Updated numbering format throughout the document.....	1
• Added standard package information and moved the comparison table to Device Comparison section.....	1
• Added description of device flow information in <i>Specifications</i>	5
• Added all chip site origin (CSO) to typical test conditions in <i>Electrical Characteristics</i>	5
• Added additional fabrication process specification for Bias Current and Bias Current vs Temperature in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for Slew Rate in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for V _{REF} Voltage Accuracy and Voltage Accuracy vs Load in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for V _{REG} Voltage Accuracy in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for V _{REG} Voltage Accuracy vs Power Supply in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for Quiescent Current in <i>Electrical Characteristics</i> table....	6
• Added all chip site origin (CSO) to typical test conditions in <i>Typical Characteristics</i>	8
• Updated Quiescent Current vs Temperature, Reference Voltage vs Temperature, Overscale Current vs Temperature, and V _{REG} Voltage vs V _{REG} Current to align with absolute maximum temperature rating in <i>Typical Characteristics</i>	8
• Added additional fabrication process curve for Quiescent Current vs Temperature in <i>Typical Characteristics</i> section.....	8
• Added <i>Device Functional Modes</i> section.....	10
• Added Power Supply Recommendations and Layout section.....	15
• Added part number fabrication process information table in <i>Device Support</i>	16

Changes from Revision D (November 2023) to Revision E (January 2026)	Page
• Updated Applications sub-bullets to TI.com web links.....	1
• Added description of device flow information in <i>Specifications</i>	5
• Added all chip site origin (CSO) to typical test conditions in <i>Electrical Characteristics</i>	5
• Added additional fabrication process specification for Bias Current and Bias Current vs Temperature in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for Slew Rate in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for V _{REG} Voltage Accuracy and Voltage Accuracy vs Power Supply in <i>Electrical Characteristics</i> table.....	6
• Added additional fabrication process specification for Quiescent Current in <i>Electrical Characteristics</i> table....	6
• Updated Quiescent Current vs Temperature, Overscale Current vs Temperature, VREG Voltage vs VREG Current, and Span Error vs Temperature to align with absolute maximum temperature rating in <i>Typical Characteristics</i>	7
• Added all chip site origin (CSO) to typical test conditions in <i>Typical Characteristics</i>	7
• Added additional fabrication process curve for Quiescent Current vs Temperature in the <i>Typical Characteristics</i>	7
• Added part number fabrication process information table in <i>Device Support</i>	15

The datasheet number will be changing.

Device Family	Change From:	Change To:
INA148	SBOS123	SBOS123A
XTR105	SBOS061C	SBOS061D
XTR11x	SBOS124B	SBOS124C
XTR117	SBOS344D	SBOS344E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/INA148>

<http://www.ti.com/product/XTR105>

<http://www.ti.com/product/XTR115>

<http://www.ti.com/product/XTR117>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact.

Changes to product identification resulting from this PCN:

None.

Product Affected:

INA148UA	INA148UA/2K5	INA148UA/2K5G4	XTR105P
XTR105P.A	XTR105PA	XTR105PA.A	XTR105UA/2K5
XTR105UA/2K5.B	XTR115U/2K5	XTR115U/2K5.B	XTR115UA/2K5

XTR115UA/2K5.B	XTR116U/2K5	XTR116U/2K5.B	XTR116UA/2K5
XTR116UA/2K5.B	XTR117AIDGKR	XTR117AIDGKR.B	XTR117AIDRBR
XTR117AIDRBR.B			

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.